

DATA SHEET

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74LVT574

3.3V Octal D-type flip-flop (3-State)

Product specification
Supersedes data of 1995 Nov 14
IC23 Data Handbook

1998 Feb 19

3.3V Octal D-type flip-flop (3-State)

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FEATURES

- Inputs and outputs on opposite side of package allow easy interface to microprocessors
- 3-State outputs for bus interfacing
- Common output enable
- TTL input and output switching levels
- Input and output interface capability to systems at 5V supply
- Bus-hold data inputs eliminate the need for external pull-up resistors to hold unused inputs
- Live insertion/extraction permitted
- No bus current loading when output is tied to 5V bus
- Power-up 3-State
- Power-up reset
- Latch-up protection exceeds 500mA per JEDEC Std 17
- ESD protection exceeds 2000V per MIL STD 883 Method 3015 and 200V per Machine Model

DESCRIPTION

The LVT574 is a high-performance BiCMOS product designed for V_{CC} operation at 3.3V.

This device is an 8-bit, edge triggered register coupled to eight 3-State output buffers. The two sections of the device are controlled independently by the clock (CP) and Output Enable ($\overline{OE}$) control gates. The state of each D input (one set-up time before the Low-to-High clock transition) is transferred to the corresponding flip-flop's Q output.

The 3-State output buffers are designed to drive heavily loaded 3-State buses, MOS memories, or MOS microprocessors. The active-Low Output Enable ($\overline{OE}$) controls all eight 3-State buffers independent of the clock operation.

When $\overline{OE}$ is Low, the stored data appears at the outputs. When $\overline{OE}$ is High, the outputs are in the High-impedance "off" state, which means they will neither drive nor load the bus.

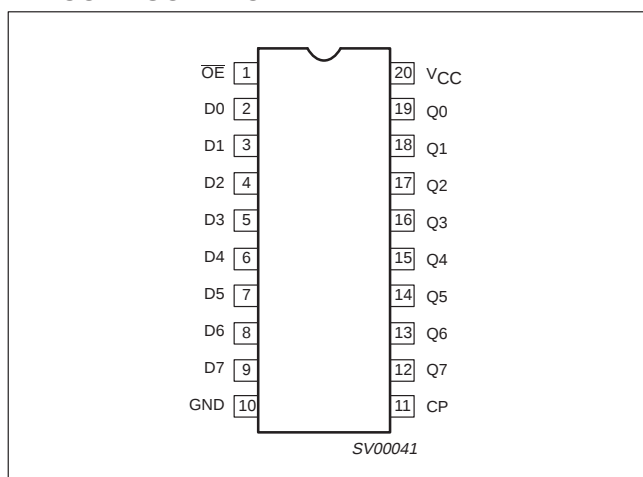
QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS $T_{amb} = 25^{\circ}\text{C}$; $GND = 0V$	TYPICAL	UNIT
t_{PLH} t_{PHL}	Propagation delay CP to Qn	$C_L = 50\text{pF}$; $V_{CC} = 3.3V$	3.6 4.3	ns
C_{IN}	Input capacitance	$V_I = 0V$ or $3.0V$	4	pF
C_{OUT}	Output capacitance	Outputs disabled; $V_{IO} = 0V$ or $3.0V$	8	pF
I_{CCZ}	Total supply current	Outputs disabled; $V_{CC} = 3.6V$	0.13	mA

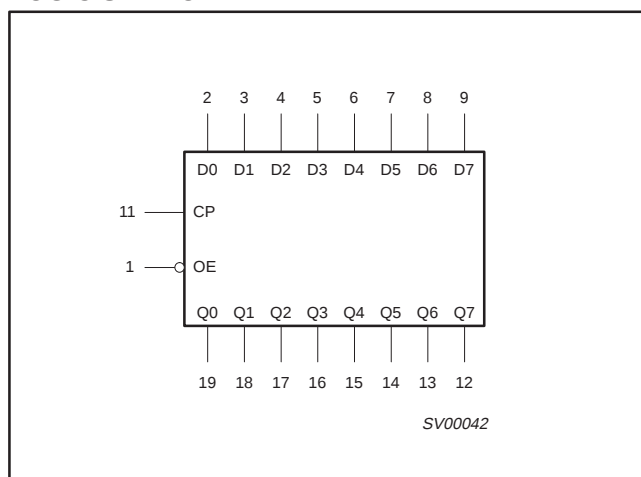
ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
20-Pin Plastic SOL	-40°C to $+85^{\circ}\text{C}$	74LVT574 D	74LVT574 D	SOT163-1
20-Pin Plastic SSOP Type II	-40°C to $+85^{\circ}\text{C}$	74LVT574 DB	74LVT574 DB	SOT339-1
20-Pin Plastic TSSOP Type I	-40°C to $+85^{\circ}\text{C}$	74LVT574 PW	74LVT574PW DH	SOT360-1

PIN CONFIGURATION



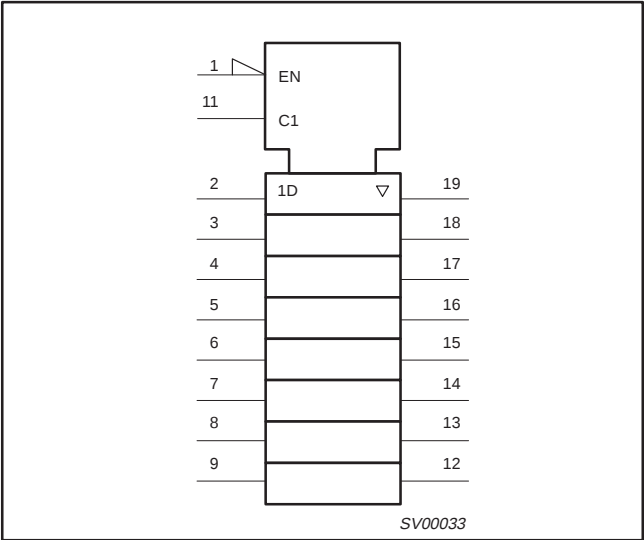
LOGIC SYMBOL



3.3V Octal D-type flip-flop (3-State)

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LOGIC SYMBOL (IEEE/IEC)



PIN DESCRIPTION

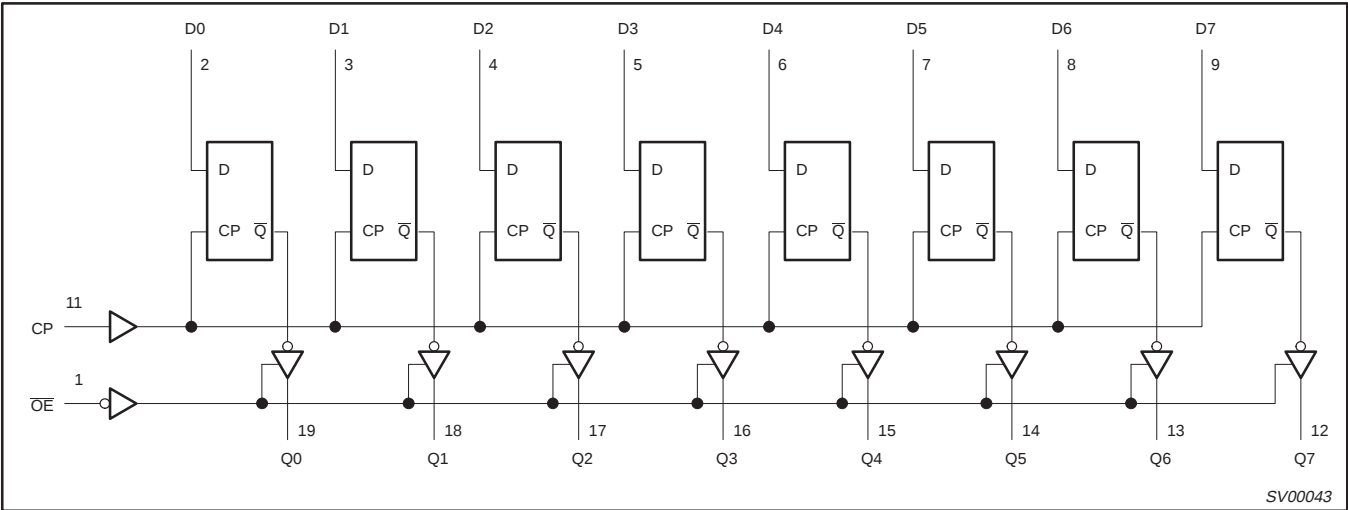
PIN NUMBER	SYMBOL	FUNCTION
1	$\overline{OE}$	Output enable input (active-low)
2, 3, 4, 5, 6, 7, 8, 9	D0-D7	Data inputs
19, 18, 17, 16, 15, 14, 13, 12	Q0-Q7	Data outputs
11	CP	Clock pulse input (active rising edge)
10	GND	Ground (0V)
20	V _{CC}	Positive supply voltage

FUNCTION TABLE

INPUTS			INTERNAL REGISTER	OUTPUTS	OPERATING MODE
$\overline{OE}$	CP	Dn		Q0 - Q7	
L	$\uparrow$	L	L	L	Load and read register
L	$\uparrow$	h	H	H	
L	$\uparrow$	X	NC	NC	Hold
H	X	X	NC	Z	Disable outputs

H = High voltage level
h = High voltage level one set-up time prior to the Low-to-High clock transition
L = Low voltage level
l = Low voltage level one set-up time prior to the Low-to-High clock transition
NC= No change
X = Don't care
Z = High impedance "off" state
 $\uparrow$ = Low-to-High clock transition
 $\uparrow$ = not a Low-to-High clock transition

LOGIC DIAGRAM



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ABSOLUTE MAXIMUM RATINGS^{1, 2}

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V_{CC}	DC supply voltage		−0.5 to +4.6	V
I_{IK}	DC input diode current	$V_I < 0$	−50	mA
V_I	DC input voltage ³		−0.5 to +7.0	V
I_{OK}	DC output diode current	$V_O < 0$	−50	mA
V_{OUT}	DC output voltage ³	Output in Off or High state	−0.5 to +7.0	V
I_{OUT}	DC output current	Output in Low state	128	mA
		Output in High state	−64	
T_{stg}	Storage temperature range		−65 to 150	°C

NOTES:

- Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150°C.
- The input and output negative voltage ratings may be exceeded if the input and output clamp current ratings are observed.

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIMITS		UNIT
		MIN	MAX	
V_{CC}	DC supply voltage	2.7	3.6	V
V_I	Input voltage	0	5.5	V
V_{IH}	High-level input voltage	2.0		V
V_{IL}	Input voltage		0.8	V
I_{OH}	High-level output current		−32	mA
I_{OL}	Low-level output current		32	mA
	Low-level output current; current duty cycle ≤ 50%, $f \geq 1\text{kHz}$		64	
$\Delta t/\Delta v$	Input transition rise or fall rate; outputs enabled		10	ns/V
T_{amb}	Operating free-air temperature range	−40	+85	°C

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DC ELECTRICAL CHARACTERISTICS

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS			UNIT
			Temp = -40°C to +85°C			
			MIN	TYP ¹	MAX	
V _{IK}	Input clamp voltage	V _{CC} = 2.7V; I _{IK} = -18mA		-0.9	-1.2	V
V _{OH}	High-level output voltage	V _{CC} = 2.7 to 3.6V; I _{OH} = -100μA	V _{CC} -0.2	V _{CC} -0.1		V
		V _{CC} = 2.7V; I _{OH} = -8mA	2.4	2.5		
		V _{CC} = 3.0V; I _{OH} = -32mA	2.0	2.2		
V _{OL}	Low-level output voltage	V _{CC} = 2.7V; I _{OL} = 100μA		0.1	0.2	V
		V _{CC} = 2.7V; I _{OL} = 24mA		0.3	0.5	
		V _{CC} = 3.0V; I _{OL} = 16mA		0.25	0.4	
		V _{CC} = 3.0V; I _{OL} = 32mA		0.3	0.5	
		V _{CC} = 3.0V; I _{OL} = 64mA		0.4	0.55	
V _{RST}	Power-up output low voltage ⁵	V _{CC} = 3.6V; I _O = 1mA; V _I = GND or V _{CC}		0.13	0.55	V
I _I	Input leakage current	V _{CC} = 0 or 3.6V; V _I = 5.5V		1	10	μA
		V _{CC} = 3.6V; V _I = V _{CC} or GND	Control pins	±0.1	±1	
		V _{CC} = 3.6V; V _I = V _{CC}	Data pins ⁴	0.1	1	
		V _{CC} = 3.6V; V _I = 0		-1	-5	
I _{OFF}	Output off current	V _{CC} = 0V; V _I or V _O = 0 to 4.5V		1	±100	μA
I _{HOLD}	Bus Hold current A inputs ⁷	V _{CC} = 3V; V _I = 0.8V	75	150		μA
		V _{CC} = 3V; V _I = 2.0V	-75	-150		
		V _{CC} = 0V to 3.6V; V _{CC} = 3.6V	±500			
I _{EX}	Current into an output in the High state when V _O > V _{CC}	V _O = 5.5V; V _{CC} = 3.0V		60	125	μA
I _{PU/PD}	Power up/down 3-State output current ³	V _{CC} ≤ 1.2V; V _O = 0.5V to V _{CC} ; V _I = GND or V _{CC} ; OE/OE = Don't care		1	±100	μA
I _{OZH}	3-State output High current	V _{CC} = 3.6V; V _O = 3V; V _I = V _{IL} or V _{IH}		1	5	μA
I _{OZL}	3-State output Low current	V _{CC} = 3.6V; V _O = 0.5V; V _I = V _{IL} or V _{IH}		1	-5	μA
I _{CCH}	Quiescent supply current ³	V _{CC} = 3.6V; Outputs High, V _I = GND or V _{CC} , I _O = 0		0.13	0.19	mA
I _{CCL}		V _{CC} = 3.6V; Outputs Low, V _I = GND or V _{CC} , I _O = 0		3	12	
I _{CCZ}		V _{CC} = 3.6V; Outputs Disabled; V _I = GND or V _{CC} , I _O = 0 ⁵		0.13	0.19	
ΔI _{CC}	Additional supply current per input pin ²	V _{CC} = 3V to 3.6V; One input at V _{CC} -0.6V, Other inputs at V _{CC} or GND		0.1	0.2	mA

NOTES:

1. All typical values are at V_{CC} = 3.3V and T_{amb} = 25°C.
2. This is the increase in supply current for each input at the specified voltage level other than V_{CC} or GND.
3. This parameter is valid for any V_{CC} between 0V and 1.2V with a transition time of up to 10msec. From V_{CC} = 1.2V to V_{CC} = 3.3V ± 0.3V a transition time of 100μsec is permitted. This parameter is valid for T_{amb} = 25°C only.
4. Unused pins at V_{CC} or GND.
5. For valid test results, data must not be loaded into the flip-flops (or latches) after applying power.
6. I_{CCZ} is measured with outputs pulled to V_{CC} or GND.
7. This is the bus hold overdrive current required to force the input to the opposite logic state.

AC CHARACTERISTICS

GND = 0V, t_R = t_F = 2.5ns, C_L = 50pF, R_L = 500Ω; T_{amb} = -40°C to +85°C.

SYMBOL	PARAMETER	WAVEFORM	LIMITS					UNIT
			V _{CC} = 3.3V ± 0.3V			V _{CC} = 2.7V		
			MIN	TYP ¹	MAX	MIN	MAX	
f _{MAX}	Maximum clock frequency	NO TAG	150			150		ns
t _{PLH} t _{PHL}	Propagation delay CP to Qn	NO TAG	1.7 2.4	3.6 4.3	5.4 5.9		6.2 6.6	ns
t _{PZH} t _{PZL}	Output enable time to High and Low level	NO TAG NO TAG	1.0 1.3	2.9 3.4	4.8 5.1		5.9 6.2	ns
t _{PHZ} t _{PLZ}	Output disable time from High and Low level	NO TAG NO TAG	1.9 1.7	4.0 3.2	5.5 4.5		5.9 4.5	ns

NOTE:

1. All typical values are at V_{CC} = 3.3V and T_{amb} = 25°C.

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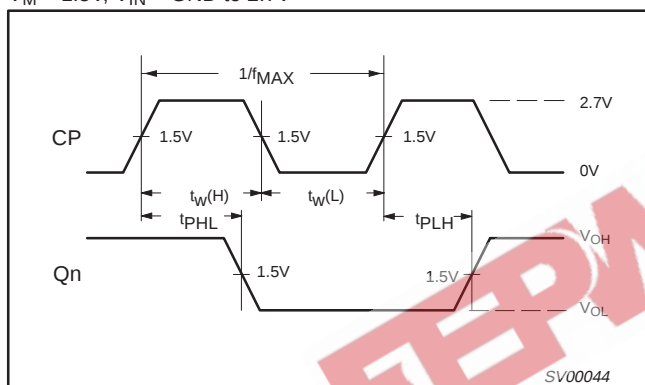
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AC SETUP REQUIREMENTS

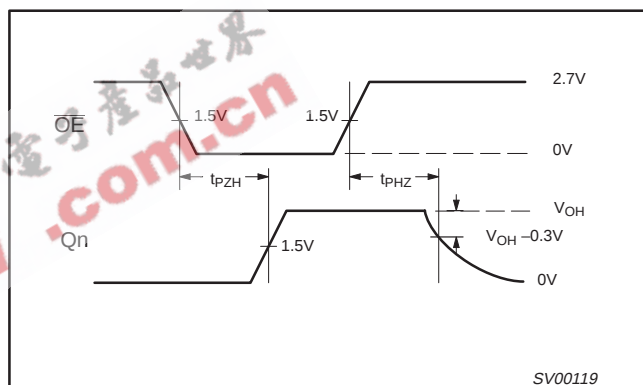
GND = 0V, $t_R = t_F = 2.5\text{ns}$, $C_L = 50\text{pF}$, $R_L = 500\Omega$; $T_{\text{amb}} = -40^\circ\text{C}$ to $+85^\circ\text{C}$.

SYMBOL	PARAMETER	WAVEFORM	LIMITS			UNIT
			$V_{CC} = 3.3V \pm 0.3V$		$V_{CC} = 2.7V$	
			MIN	MAX	MIN	
$t_{S(H)}$ $t_{S(L)}$	Setup time, High or Low, Dn to CP	NO TAG	2.0 2.0		2.4 2.4	ns
$T_{H(H)}$ $T_{H(L)}$	Hold time, High or Low, Dn to CP	NO TAG	0.3 0.3		0 0	ns
$T_W(H)$	CP pulse width High or Low	NO TAG	3.3 3.3		3.3 3.3	ns

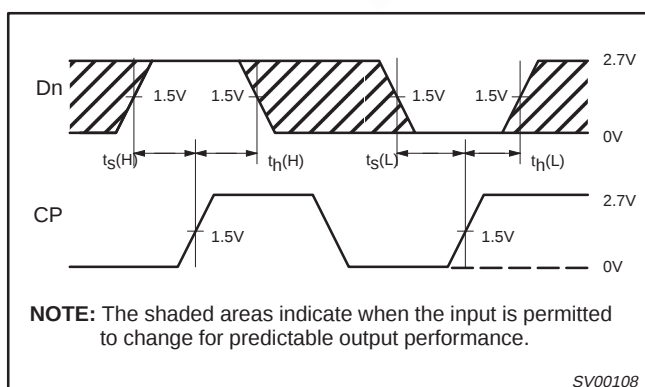
AC WAVEFORMS

 $V_M = 1.5V$, $V_{IN} = \text{GND to } 2.7V$ 

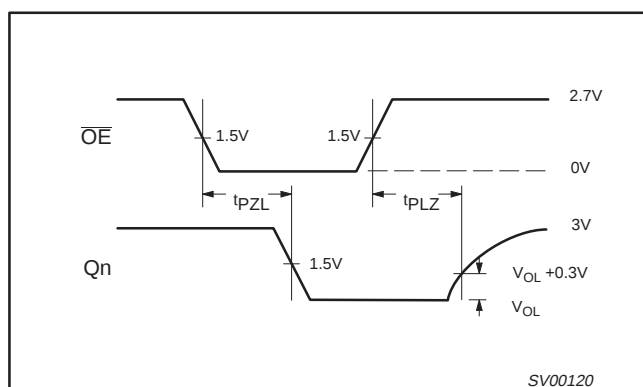
Waveform 1. Propagation Delay, Clock Input to Output, Clock Pulse Width, and Maximum Clock Frequency



Waveform 3. 3-State Output Enable Time to High Level and Output Disable Time from High Level



Waveform 2. Data Setup and Hold Times

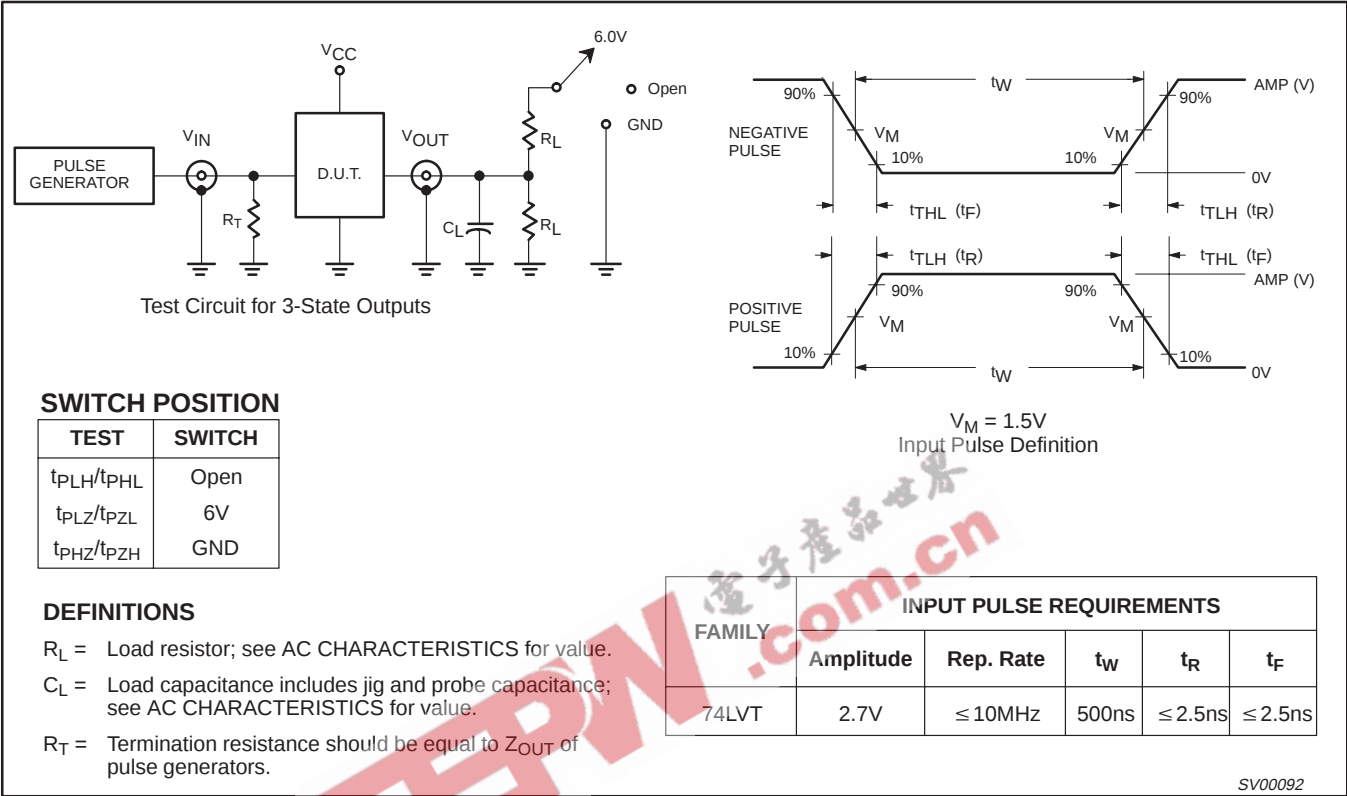


Waveform 4. 3-State Output Enable Time to Low Level and Output Disable Time from Low Level

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TEST CIRCUIT AND WAVEFORM

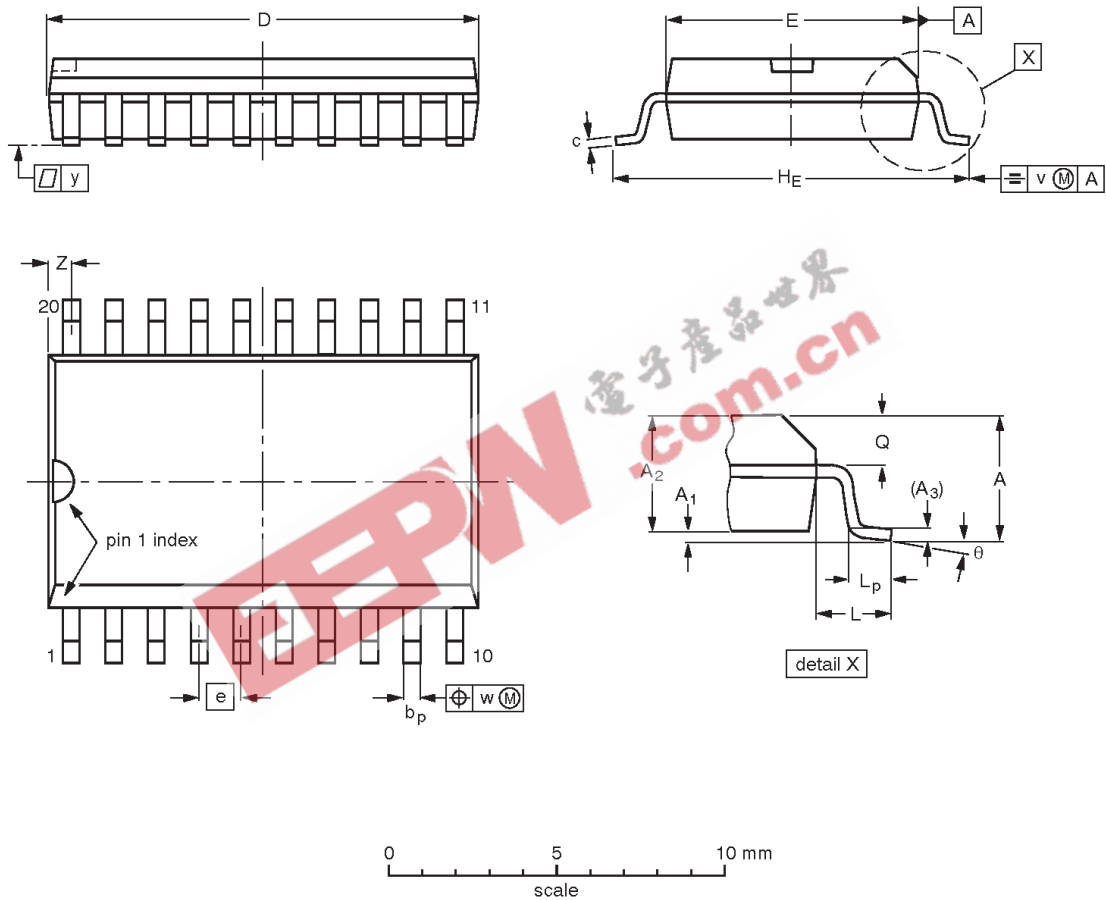


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SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8° 0°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.050	0.42 0.39	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

Note
1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

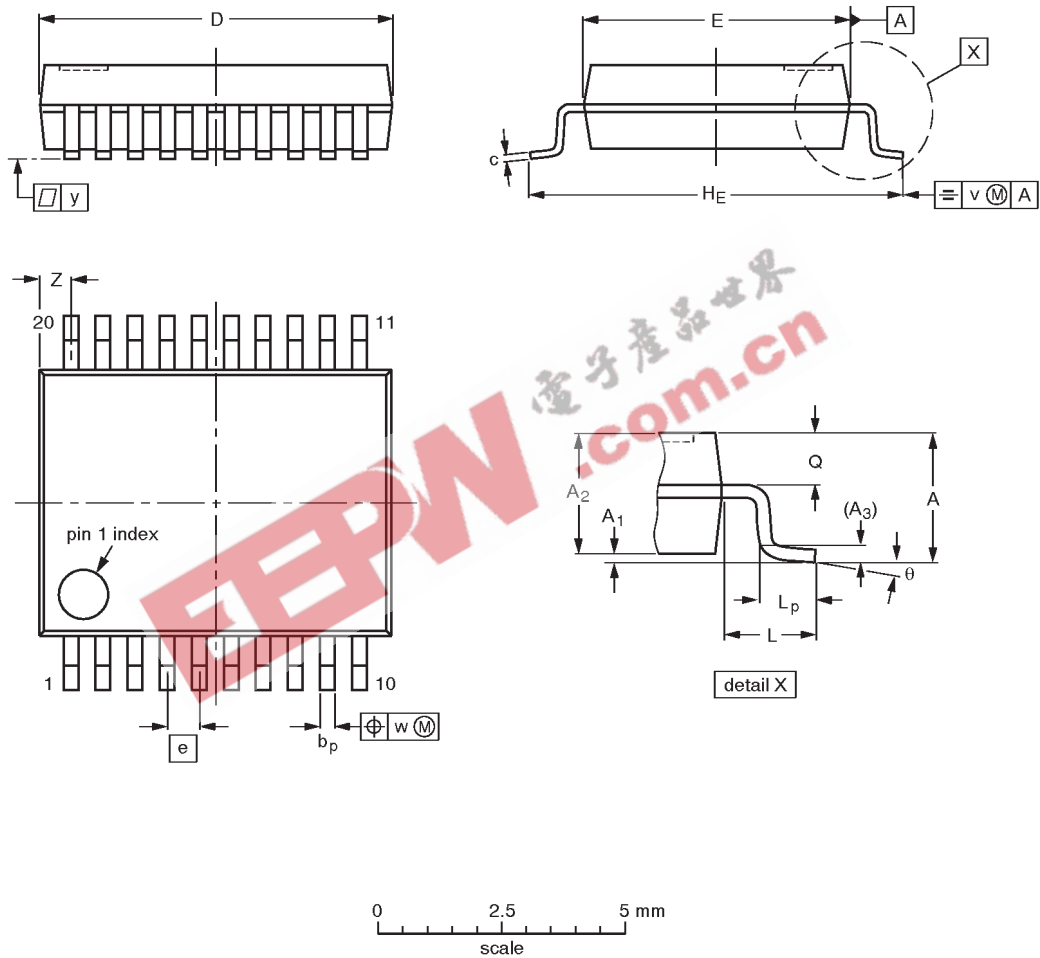
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT163-1	075E04	MS-013AC				92-11-17 95-01-24

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SSOP20: plastic shrink small outline package; 20 leads; body width 5.3 mm

SOT339-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	z ⁽¹⁾	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	7.4 7.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	0.9 0.5	8° 0°

Note
1. Plastic or metal protrusions of 0.20 mm maximum per side are not included.

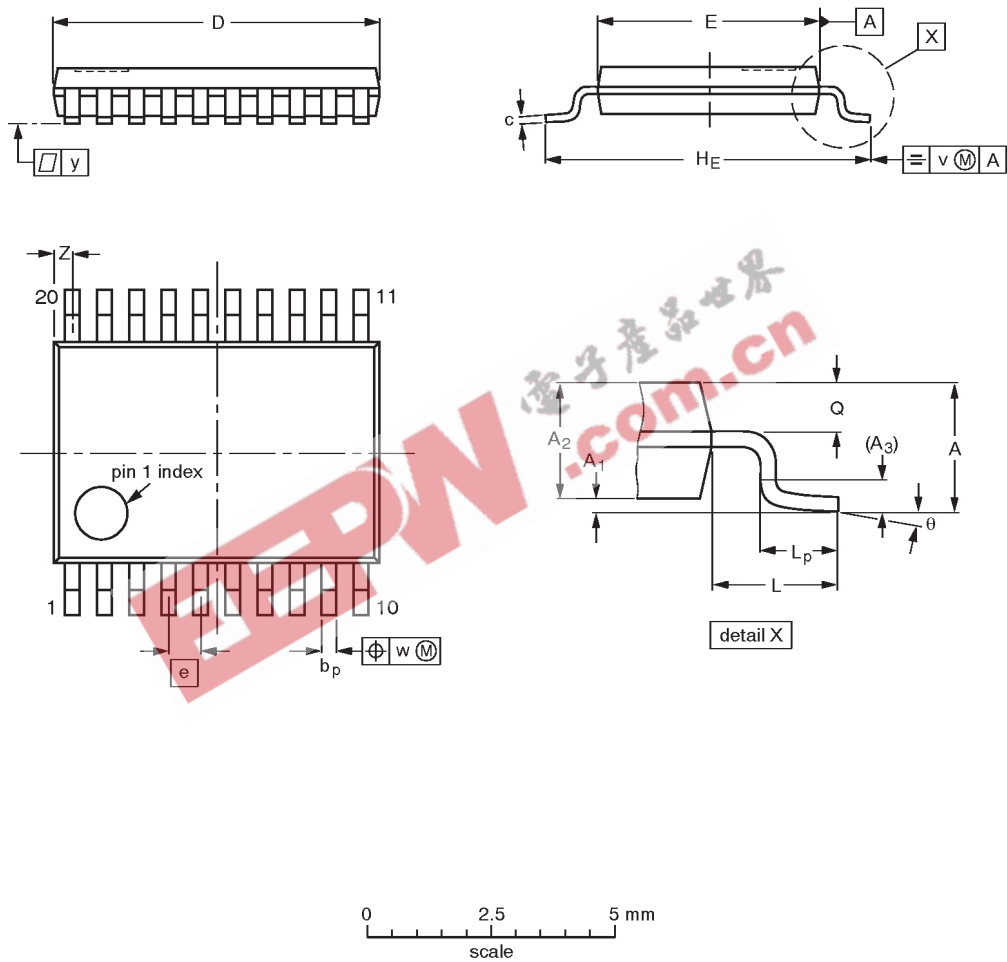
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT339-1		MO-150AE				93-09-08 95-02-04

3.3V Octal D-type flip-flop (3-State)

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TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm

SOT360-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽²⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	6.6 6.4	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8° 0°

Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT360-1		MO-153AC				-93-06-16- 95-02-04

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NOTES

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Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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[1] Please consult the most recently issued datasheet before initiating or completing a design.

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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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